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December 2013

FPAB30BH60B PFC SPM[®] 3 Series for Single-Phase Boost PFC

Features

- UL Certified No. E209204 (UL1557)
- 600 V 30 A Single-Phase Boost PFC with Integral Gate Driver and Protection
- Very Low Thermal Resistance Using Al₂O₃ DBC Substrate
- Full-Wave Bridge Rectifier and High-Performance Output Diode
- · Built-in NTC Thermistor for Temperature Monitoring
- · Optimized for 20kHz Switching Frequency
- · Isolation Rating: 2500 Vrms/min.

Applications

· Single-Phase Boost PFC Converter

Related Source

- AN-9090 PFC SPM 3 Series User's Guide
- AN-9091 Boost PFC Inductor Design Guide

General Description

The FPAB30BH60B is an advanced PFC SPM® 3 module providing a fully-featured, high-performance Boost PFC (Power Factor Correction) input power stage for consumer, medical, and industrial applications. These single-phase modules integrate optimized gate drive of the built-in IGBT to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockout, over-current shutdown, thermal monitoring, and fault reporting. These modules also feature a full-wave rectifier, and high-performance output diode for additional space savings and mounting convenience.

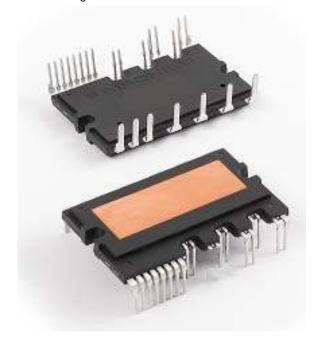


Figure 1. Package Overview

Package Marking & Ordering Information

| Device | Device Marking | e Marking Package Pac | | Quantity |
|-------------|----------------|-----------------------|------|----------|
| FPAB30BH60B | FPAB30BH60B | SPMIC-027 | Rail | 10 |

Integrated Power Functions

• PFC converter for single-phase AC / DC power conversion (please refer to Figure 3)

Integrated Drive, Protection, and System Control Functions

- For IGBTs: gate drive circuit, Over-Current Protection (OCP), control supply circuit Under-Voltage Lock-Out (UVLO) Protection
- Fault signal: corresponding to OC and UV fault
- · Built-in thermistor: temperature monitoring
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

Pin Configuration

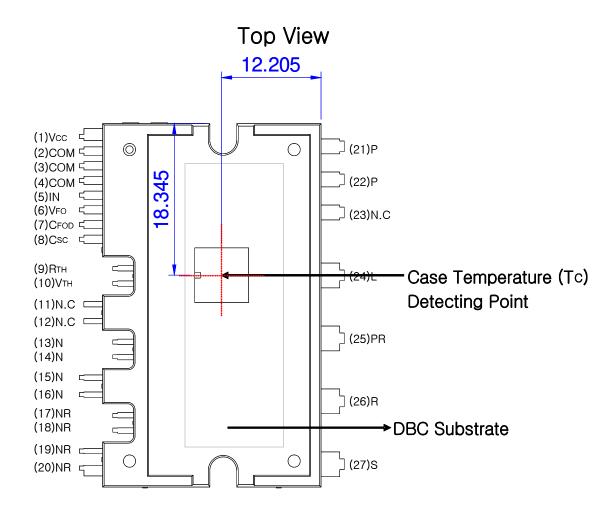


Figure 2. Top View

Notes :

1. For the measurement point of case temperature (T_C) , please refer to Figure 2.

Pin Descriptions

| Pin Number | Pin Name | Pin Description |
|------------|-------------------|--|
| 1 | V _{CC} | Common Bias Voltage for IC and IGBT Driving |
| 2,3,4 | СОМ | Common Supply Ground |
| 5 | IN | Signal Input for IGBT |
| 6 | V_{FO} | Fault Output |
| 7 | C _{FOD} | Capacitor for Fault Output Duration Selection |
| 8 | C _{SC} | Capacitor (Low-Pass Filter) for Over-Current Detection |
| 9 | R _(TH) | Series Resistor for The Use of Thermistor |
| 10 | V _(TH) | Thermistor Bias Voltage |
| 11,12 | N.C | No Connection* |
| 13~16 | N | IGBT Emitter |
| 17~20 | N _R | Negative DC-Link of Rectifier |
| 21,22 | Р | Positive Rail of DC-Link |
| 23 | N.C | No Connection |
| 24 | L | Reactor Connection Pin |
| 25 | P _R | Positive DC-Link of Rectifier |
| 26 | R | AC Input for R-Phase |
| 27 | S | AC Input for S-Phase |

^{* 11}th and 12th pins are cut. Please refer to package outline drawings for more detail.

Internal Equivalent Circuit and Input/Output Pins

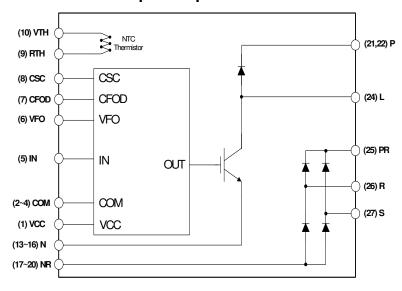


Figure 3. Internal Block Diagram

Absolute Maximum Ratings ($T_J = 25$ °C, unless otherwise specified.) **Converter Part**

| Symbol | Item | Item Condition | | Unit |
|------------------------|------------------------------------|--|-----------|------------------|
| V _i | Supply Voltage | Applied between R - S | 264 | V _{rms} |
| V _{i(Surge)} | Supply Voltage (Surge) | Applied between R - S | 500 | ٧ |
| V _{PN} | Output Voltage | Applied between P - N | 450 | ٧ |
| V _{PN(Surge)} | Output Voltage (Surge) | Applied between P - N | 500 | ٧ |
| V _{CES} | Collector - Emitter Voltage | | 600 | ٧ |
| I _C | Each IGBT Collector Current | T _C = 25°C, T _J < 150°C | 30 | Α |
| I _{CP} | Each IGBT Collector Current (Peak) | T _C = 25°C, T _J < 150°C, Under 1ms Pulse Width | 60 | Α |
| P _C | Collector Dissipation | T _C = 25°C | 104 | W |
| V _{RRM} | Repititive Peak Reverse Voltage | | 600 | V |
| I _{FSM} | Peak Forward Surge Current | Single Half Sine-Wave | 350 | Α |
| TJ | Operating Junction Temperature | | -40 ~ 150 | °C |

Control Part

| Symbol | Item | Condition | Rating | Unit |
|-----------------|-------------------------------|---------------------------------------|-----------------------------|----------|
| V _{CC} | Control Supply Voltage | Applied between V _{CC} - COM | 20 | V |
| V _{IN} | Input Signal Voltage | Applied between IN - COM | -0.3 ~ V _{CC} +0.3 | V |
| V _{FO} | Fault Output Supply Voltage | Applied between V _{FO} - COM | -0.3 ~ V _{CC} +0.3 | V |
| I _{FO} | Fault Output Current | Sink Current at V _{FO} Pin | 5 | mA |
| V _{SC} | Current Sensing Input Voltage | Applied between C _{SC} - COM | -0.3 ~ V _{CC} +0.3 | V |

Total System

| Symbol | Item | Condition | Rating | Unit |
|------------------|---------------------|---|-----------|------------------|
| T _{STG} | Storage Temperature | | -40 ~ 125 | °C |
| V _{ISO} | Isolation Voltage | 60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat Sink Plate | 2500 | V _{rms} |

Thermal Resistance

| Symbol | Item | Condition | Min. | Тур. | Max. | Unit |
|---------------------------|-------------------------------------|------------------------------|------|------|------|------|
| $R_{\theta(j-c)Q}$ | Junction to Case Thermal Resistance | IGBT | - | - | 1.2 | °C/W |
| $R_{\theta(j\text{-}c)F}$ | | FRD | - | - | 1.4 | °C/W |
| $R_{\theta(j\text{-}c)R}$ | | Rectifier (per 1 / 4 module) | - | - | 1.7 | °C/W |

Electrical Characteristics ($T_J = 25$ °C, unless otherwise specified.)

Converter Part

| Symbol | Item | Condition | Min. | Тур. | Max. | Unit |
|----------------------|--|---|------|------|------|------|
| V _{CE(SAT)} | IGBT Saturation Voltage | V _{CC} = 15 V, V _{IN} = 5 V, I _C = 30 A | - | 2.2 | 2.8 | V |
| V _{FF} | FRD Forward Voltage | I _F = 30 A | - | 1.9 | 2.6 | V |
| V_{FR} | Rectifier Forward Voltage | I _F = 30 A | 1 | 1.2 | 1.5 | V |
| t _{ON} | Switching Times | V _{PN} = 400 V, V _{CC} = 15V, I _C = 30 A | 1 | 500 | - | ns |
| t _{C(ON)} | | $V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$, Inductive Load | - | 200 | - | ns |
| t _{OFF} | | (Note 2) | 1 | 420 | - | ns |
| t _{C(OFF)} | | | ı | 100 | - | ns |
| t _{rr} | | | - | 60 | - | ns |
| I _{rr} | | | 1 | 7 | - | Α |
| I _{CES} | Collector - Emitter Leakage Current | V _{CE} = V _{CES} | - | - | 250 | μА |

Notes:
2. t_{ON} and t_{OFF} include the propagation delay of the internal drive IC. t_{C(ON)} and t_{C(OFF)} are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

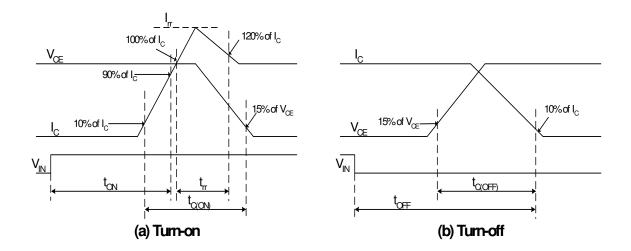


Figure 4. Switching Time Definition

Control Part

| Symbol | Item | Condition | Min. | Тур. | Max. | Unit |
|----------------------|--|--|------|------|------|----------|
| I _{QCCL} | Quiescent V _{CC} Supply Current | V _{CC} = 15 V, IN = 0 V V _{CC} - COM | - | - | 26 | mA |
| V _{FOH} | Fault Output Voltage | $V_{SC} = 0 \text{ V}, V_{FO} \text{ Circuit: } 4.7 \text{ k}\Omega \text{ to } 5 \text{ V Pull-up}$ | 4.5 | - | - | ٧ |
| V _{FOL} | | $V_{SC} = 1 \text{ V}, V_{FO} \text{ Circuit: } 4.7 \text{ k}\Omega \text{ to } 5 \text{ V Pull-up}$ | - | - | 0.8 | ٧ |
| V _{SC(ref)} | Over-Current Trip Level | V _{CC} = 15 V | | 0.50 | 0.55 | V |
| UV _{CCD} | Supply Circuit Under-Voltage | Detection Level | 10.7 | 11.9 | 13.0 | ٧ |
| UV _{CCR} | Protection | Reset Level | 11.2 | 12.4 | 13.2 | ٧ |
| t _{FOD} | Fault-Out Pulse Width | C _{FOD} = 33 nF (Note 3) | 1.4 | 1.8 | 2.0 | ms |
| V _{IN(ON)} | ON Threshold Voltage | Applied between IN - COM | 2.8 | - | - | ٧ |
| V _{IN(OFF)} | OFF Threshold Voltage | | - | - | 0.8 | V |
| R _{TH} | Resistance of Thermistor | at T _{TH} = 25°C (Note 4, Figure 5) | - | 47.0 | - | kΩ |
| | | at T _{TH} = 100°C (Note 4, Figure 5) | - | 2.9 | - | kΩ |

Notes:
3. The fault-out pulse width t_{FOD} depends on the capacitance value of C_{FOD} according to the following approximate equation: $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}$ [F].

4. T_{TH} is the temperature of know case temperature (T_C) , please make the experiment considering your application.

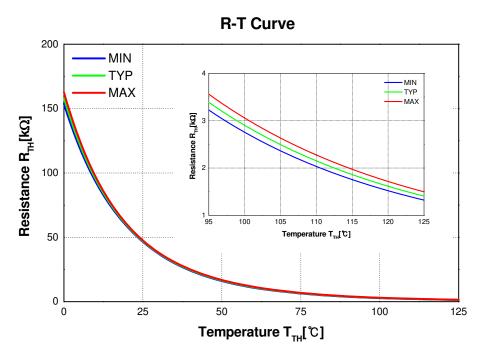


Figure 5. R-T Curve of the Built-In Thermistor

Recommended Operating Condition

| Symbol | Item | Condition | Min. | Тур. | Max. | Unit |
|----------------------|--------------------------|---|------|------|------|-------------------|
| V _i | Input Supply Voltage | Applied between R - S | 187 | 220 | 253 | V _{rms} |
| V _{PN} | Output Voltage | Applied between P - N | - | 380 | 400 | ٧ |
| V _{CC} | Control Supply Voltage | Applied between V _{CC(L)} - COM | 13.5 | 15.0 | 16.5 | ٧ |
| dV _{CC} /dt | Control Supply Variation | | -1 | - | 1 | V/µs |
| f _{PWM} | PWM Input Frequency | T _J ≤ 150°C | - | 20 | - | kHz |
| l _i | Allowable Input Current | T _C < 90°C, V _i = 220 V, V _{PN} = 380 V V _{PWM} = 20 kHz | - | - | 30 | A _{peak} |

Mechanical Characteristics and Ratings

| Item | Co | ndition | Min. | Тур. | Max. | Unit |
|-----------------|--------------------|----------------------|------|-------|------|------|
| Mounting Torque | Mounting Screw: M3 | Recommended 0.62 N•m | 0.51 | 0.62 | 0.72 | N•m |
| Device Flatness | See Figure 6 | | 0 | - | +120 | μm |
| Weight | | | - | 15.00 | - | g |

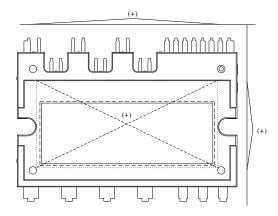
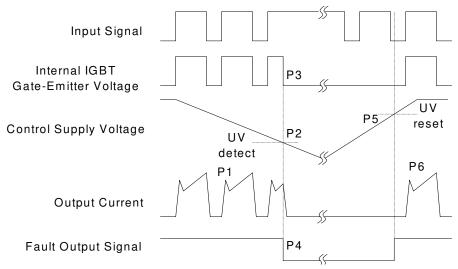


Figure 6. Flatness Measurement Position

Time Charts of Protective Function

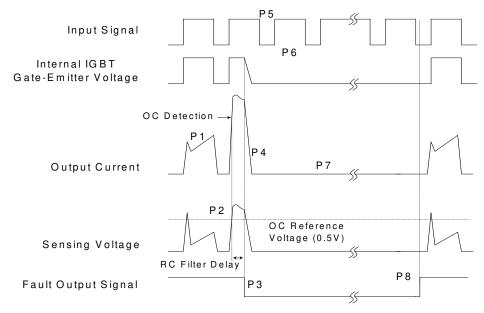


P1: Normal operation: IGBT ON and conducting current.

P2: Under-voltage detection. P3: IGBT gate interrupt. P4: Fault signal generation. P5: Under-voltage reset.

P6: Normal operation: IGBT ON and conducting current.

Figure 7. Under-Voltage Protection



P1: Normal operation: IGBT ON and conducting current.

P2 : Over current detection.

P3: IGBT gate interrupt / fault signal generation.

P4: IGBT is slowly turned off.

P5: IGBT OFF signal.

P6 : IGBT ON signa: but IGBT cannot be turned on during the fault output activation.

P7: IGBT OFF state.

P8 : Fault output reset and normal operation start.

Figure 8. Over-Current Protection

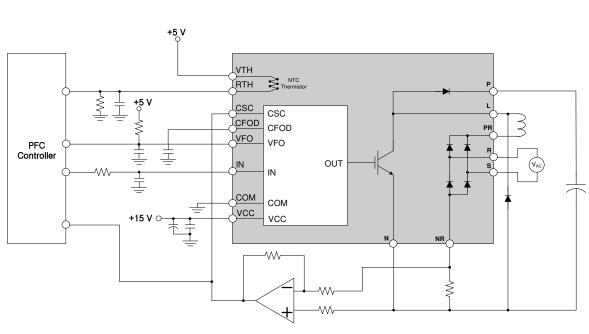


Figure 9. Application Example

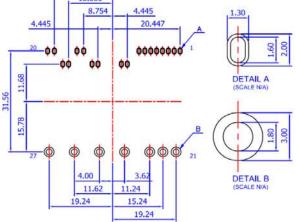
Notes:

- 5. Each capacitors should be located as close to PFC SPM® product pins as possible. 6. It's recommended that anti-parallel diode should be connected with IGBT.

Detailed Package Outline Drawings (0.136)(0.30)(0.70) 2XLEAD PITCH (TOLERANCE: ±0.30) A: 1.778 (2.31)(1.55)B: 2.050 C: 2.531 8.20 7.60 3.20 (13.20) 1.50 (R0.70) 13,335 4.30 4.445 (2.76) 2X 8.754 20.447 (1.50)89. фф DETAIL A (0.70) 2X31.56 4.30 2X 15.78 1.40 7X 1.20 7X

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